

IN THE SPECIFICATION:

Please amend paragraph number [0031] as follows:

[0031] Referring to drawing FIG. 4, the adhesive tape 130 is adhesively placed and attached to the conductive bumps 120 to overlie the front surface 112 of the wafer 110. The adhesive tape 130 is preferably substantially the size of the wafer 110 so that it overlies each of the conductive bumps 120. The adhesive tape 130 may also overlie portions of the wafer 110 without the conductive bumps 120 thereon, namely a periphery of the front surface 112, to provide protection of the front surface 112. Such positioning of the adhesive tape 130 may be accomplished manually and/or by machinery.

Please amend paragraph number [0032] as follows:

[0032] As depicted in drawing FIG. 4, the adhesive 132 attached to the conductive bumps 120 may conform to and/or abut the conductive bumps 120 so that the adhesive 132 attaches between about 10% and about 60% of the bumps' surface area. The range of necessary surface area for sufficient attaching depends on the type of adhesive 132 employed, as known in the art. As such, it is desired that the adhesive 132 has sufficient strength to withstand a grinding process (discussed further below). Further, an important feature of the present invention is that the adhesive tape 130 conforms to the conductive bumps 120 in a manner that allows the outer surface 138 of the backing 136 to be substantially planar.

Please amend paragraph number [0033] as follows:

[0033] Referring to drawing FIG. 5, there is shown ~~a cross-sectional~~ cross-sectional view of the wafer 110 and a wafer mounting chuck 150 prior to the wafer 110 being mounted thereon. As shown, the wafer 110 is inverted with its front surface 112 facedown so that the substantially planar outer surface 138 of the backing 136 of the adhesive tape 130 is facing the wafer mounting chuck 150. The wafer mounting chuck 150 includes a suction surface 152 on which the substantially planar outer surface 138 is to be attached or mounted. The suction surface 152 includes apertures 154 that communicate with the chamber 156 in the wafer

mounting chuck 150. The chamber 156 in turn communicates with a vacuum 160 which provides suction at the suction surface 152. The vacuum 160 is integrated with a mounting apparatus 162 to which the wafer mounting chuck 150 is connected. The number of apertures 154 in the suction surface 152 may vary depending on the required suction involved, which may be determined by one of ordinary skill in the art. For example, a plurality of closely spaced, minuscule apertures 154 having small diameters may be provided. Alternatively, the apertures 154 may be larger and more spread out.

Please amend paragraph number [0035] as follows:

[0035] The back surface 114 of the wafer 110 is then processed through a normal-back-grind ~~grind~~ back-grind or back-lap process to thin the wafer 110 to a desired thickness by a grinder 164. The grinder 164, as depicted in drawing FIG. 6, is only intended to represent a generic wafer-back-grinding ~~back-grinding~~ tool. In the grinding operation, the wafer 110 may be moved to successive grinding stations with grinding wheels of decreasing grain size and abrasiveness so that the roughness of the back surface 114 is successively decreased. As such, the wafer 110 is thinned to a predetermined thickness 168 (FIG. 7) of less than about 12 mils and, preferably, the wafer is thinned to between about 6 mils and about 12 mils, although the wafer may be thinned to any desired thickness, such as less than 6 mils.